

**AMENDMENTS TO THE CLAIMS:**

Please cancel Claims 2, 4-11, 16-17, and 19-45, and amend Claim 1 as follows:

1. (Currently amended) A method of fabricating a micromechanical device, the method comprising:
  - forming at least two micromechanical devices on a common substrate;
  - applying a liquid overcoat material to said micromechanical devices;
  - distributing said material using ultrasonic energy;
  - separating said common substrate to separate said devices; and
  - removing said overcoat from said micromechanical devices.
2. (Canceled)
3. The method of Claim 1, said applying a liquid overcoat material comprising:
  - applying said liquid overcoat material to said common substrate; and
  - spinning said common substrate to disperse said liquid overcoat material.
- 4-11. (Canceled)
12. The method of Claim 1, comprising:
  - curing said liquid overcoat material.
13. The method of Claim 1, comprising:
  - curing said liquid overcoat material by heating said liquid overcoat material.
14. The method of Claim 1, comprising:
  - curing said liquid overcoat material using ultraviolet light.
15. The method of Claim 1, said applying a liquid overcoat material to said micromechanical devices comprising:
  - applying a urethane acrylate resin.
- 16-17. (Canceled)
18. The method of Claim 1, said removing said overcoat from said micromechanical devices comprising:
  - removing said overcoat using an isotropic etch.
- 19-45. (Canceled)